## IEEE P802.3cd Ad Hoc Report

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# Report

- Charter: to discuss topics towards supporting the developed objectives, PAR and CSD or for providing the Task Force with contributions to help it prepare for future decisions.
- 5 ad hoc calls since May 2017 Interim
  - June 7, June 14, June 21, June 28, July 5
  - 50+ attendees
  - 15 contributions presented (see next slide)
- Meeting minutes and presentation materials: <a href="http://www.ieee802.org/3/cd/public/adhoc/archive/index.html">http://www.ieee802.org/3/cd/public/adhoc/archive/index.html</a>
- Further work: continue to refine content towards future drafts and address gaps in the specification
- Next meeting: To be announced over the email reflector (Assume July 26 @ 8am Pacific)

## Joint Ad Hoc Clarification

- Some of the 802.3cd ad hoc meetings were also a joint ad hoc with the 802.3bs <u>electrical</u> <u>track</u> to focus on common issues related to both groups.
- For example, topics like COM were in scope for these joint meetings
  - These were not full P802.3bs ad hoc meetings

### Presentations

#### P802.3cd TF Ad Hoc –

- "D-Optimal DOE of all COM parameters", Richard Mellitz
- "Operational Reflection Impact (ORI) using pulse TDR", Richard Mellitz
- "Summary of COM problems between channel and Rx Interference Tolerance Test", Yasuo Hidaka
- "Implementing an Extinction Ratio of 3.5 dB in 50GBASE-FR/LR in P802.3cd", Peter Stassar
- "Resolving COM and RX ITT Concerns", Adee Ran
- "Return Loss of Test Channel for Rx ITT", Yasuo Hidaka
- "Tightening Channel Variation by Nominal Impedance Values of COM Package Model", Yasuo Hidaka
- "C2C Precode and TxEq hand shaking", Jeff Slavick
- "PMD Link Training issues", Jeff Slavick
- "Return loss of Test Channel for Rx ITT in Clause 136 (#72)", Yasuo Hidaka

#### P802.3cd & P802.3bs Electrical common topics

- "Open Electrical Issues", Piers Dawe
- "Optional FEC degrade monitor feature for 50G and 100G FEC", Gary Nicholl
- "CL 136 Link Training Update Request Behavior", Zvi Rechtman
- "Package impedance and termination effect on COM (update)", Mike Dudek
- "Concerns with stressed input tests in Annex 120E D3p2", Steve Sekel

## **THANKS!**